## **Complementary Silicon High-Power Transistors**

Designed for general-purpose power amplifier and switching applications.



- 25 A Collector Current
- Low Leakage Current -

 $I_{CFO} = 1.0 \text{ mA}$  @ 30 and 60 V

• Excellent DC Gain -

 $h_{FE} = 40 \text{ Typ } @ 15 \text{ A}$ 

• High Current Gain Bandwidth Product -

 $|h_{fe}| = 3.0 \text{ min } @ I_{C}$ = 1.0 A, f = 1.0 MHz

• These are Pb-Free Devices\*

#### **MAXIMUM RATINGS**

Rating	Symbol	TIP35A TIP36A	TIP35B TIP36B	TIP35C TIP36C	Unit
Collector - Emitter Voltage	$V_{CEO}$	60	80	100	Vdc
Collector - Base Voltage	V <sub>CB</sub>	60	80	100	Vdc
Emitter - Base Voltage	V <sub>EB</sub>		5.0		Vdc
Collector Current - Continuous - Peak (Note 1)	Ic	25 40		Adc	
Base Current - Continuous	Ι <sub>Β</sub>		5.0		Adc
Total Power Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>		125		W W/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	_	-65 to +150	0	°C
Unclamped Inductive Load	E <sub>SB</sub>		90	_	mJ

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.0	°C/W
Junction-To-Free-Air Thermal Resistance	$R_{\theta JA}$	35.7	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

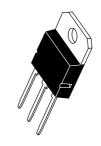
1. Pulse Test: Pulse Width = 10 ms, Duty Cycle ≤ 10%.



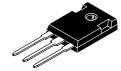
ON Semiconductor®

http://onsemi.com

# 25 AMPERE COMPLEMENTARY SILICON POWER TRANSISTORS 60-100 VOLTS, 125 WATTS



SOT-93 (TO-218) CASE 340D STYLE 1



TO-247 CASE 340L STYLE 3

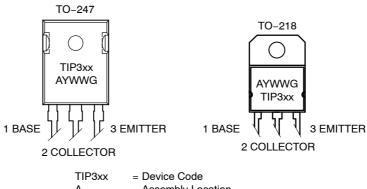
NOTE: Effective June 2012 this device will be available only in the TO-247 package. Reference FPCN# 16827.

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **MARKING DIAGRAMS**



 A
 = Assembly Location

 Y
 = Year

 WW
 = Work Week

 G
 = Pb-Free Package

#### **ORDERING INFORMATION**

Device	Package	Shipping
TIP35AG	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP35BG	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP35CG	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP36AG	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP36BG	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP36CG	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP35AG	TO-247 (Pb-Free)	30 Units / Rail
TIP35BG	TO-247 (Pb-Free)	30 Units / Rail
TIP35CG	TO-247 (Pb-Free)	30 Units / Rail
TIP36AG	TO-247 (Pb-Free)	30 Units / Rail
TIP36BG	TO-247 (Pb-Free)	30 Units / Rail
TIP36CG	TO-247 (Pb-Free)	30 Units / Rail

### **ELECTRICAL CHARACTERISTICS** ( $T_C = 25$ °C unless otherwise noted)

Characteri	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS			1	•	•
Collector–Emitter Sustaining Voltage (Note 2) $(I_C = 30 \text{ mA}, I_B = 0)$	TIP35A, TIP36A TIP35B, TIP36B TIP35C, TIP36C	V <sub>CEO(sus)</sub>	60 80 100	- - -	Vdc
Collector–Emitter Cutoff Current $(V_{CE} = 30 \text{ V}, I_B = 0)$ $(V_{CE} = 60 \text{ V}, I_B = 0)$	TIP35A, TIP36A TIP35B, TIP35C, TIP36B, TIP36C	I <sub>CEO</sub>	- -	1.0 1.0	mA
Collector–Emitter Cutoff Current $(V_{CE} = Rated V_{CEO}, V_{EB} = 0)$		I <sub>CES</sub>	_	0.7	mA
Emitter-Base Cutoff Current $(V_{EB} = 5.0 \text{ V}, I_{C} = 0)$		I <sub>EBO</sub>	-	1.0	mA
ON CHARACTERISTICS (Note 2)					
DC Current Gain ( $I_C = 1.5 \text{ A}, V_{CE} = 4.0 \text{ V}$ ) ( $I_C = 15 \text{ A}, V_{CE} = 4.0 \text{ V}$ )		h <sub>FE</sub>	25 15	- 75	-
Collector–Emitter Saturation Voltage ( $I_C = 15 \text{ A}, I_B = 1.5 \text{ A}$ ) ( $I_C = 25 \text{ A}, I_B = 5.0 \text{ A}$ )		V <sub>CE(sat)</sub>	-	1.8 4.0	Vdc
Base–Emitter On Voltage ( $I_C$ = 15 A, $V_{CE}$ = 4.0 V) ( $I_C$ = 25 A, $V_{CE}$ = 4.0 V)		V <sub>BE(on)</sub>	- -	2.0 4.0	Vdc
DYNAMIC CHARACTERISTICS					
Small-Signal Current Gain ( $I_C = 1.0 \text{ A}, V_{CE} = 10 \text{ V}, f = 1.0 \text{ kHz}$ )		h <sub>fe</sub>	25	_	_
Current-Gain — Bandwidth Product (I <sub>C</sub> = 1.0 A, V <sub>CE</sub> = 10 V, f = 1.0 MHz)		f <sub>T</sub>	3.0	-	MHz

<sup>2.</sup> Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

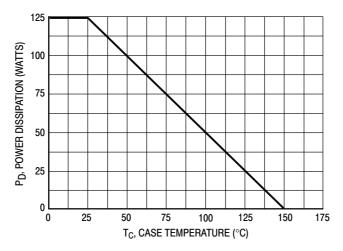
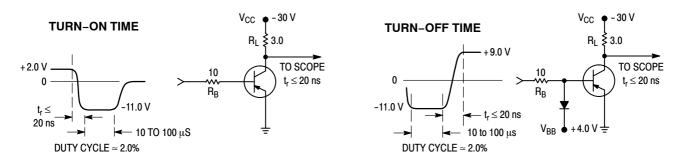


Figure 1. Power Derating



FOR CURVES OF FIGURES 3 & 4,  $R_B$  &  $R_L$  ARE VARIED. INPUT LEVELS ARE APPROXIMATELY AS SHOWN. FOR NPN, REVERSE ALL POLARITIES.

Figure 2. Switching Time Equivalent Test Circuits

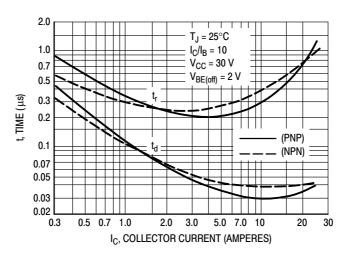


Figure 3. Turn-On Time

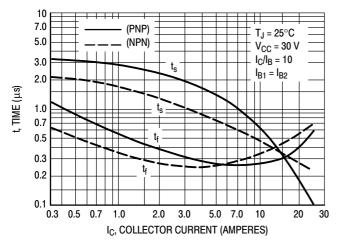


Figure 4. Turn-Off Time

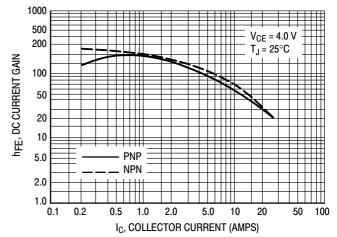


Figure 5. DC Current Gain

#### **FORWARD BIAS**

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 6 is based on  $T_C = 25^{\circ}C$ ;  $T_{J(pk)}$  is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when  $T_C \ge 25^{\circ}C$ . Second breakdown limitations do not derate the same as thermal limitations.

#### **REVERSE BIAS**

For inductive loads, high voltage and high current must be sustained simultaneously during turn-off, in most cases, with the base to emitter junction reverse biased. Under these conditions the collector voltage must be held to a safe level at or below a specific value of collector current. This can be accomplished by several means such as active clamping, RC snubbing, load line shaping, etc. The safe level for these devices is specified as Reverse Bias Safe Operating Area and represents the voltage-current conditions during reverse biased turn-off. This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode. Figure 7 gives RBSOA characteristics.

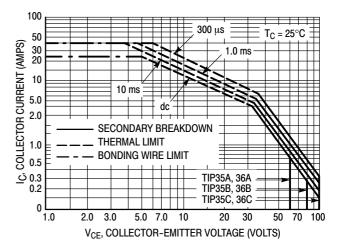


Figure 6. Maximum Rated Forward Bias Safe Operating Area

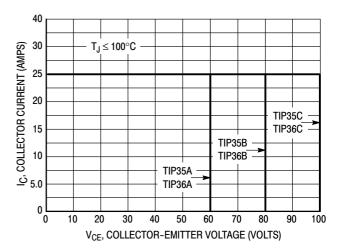
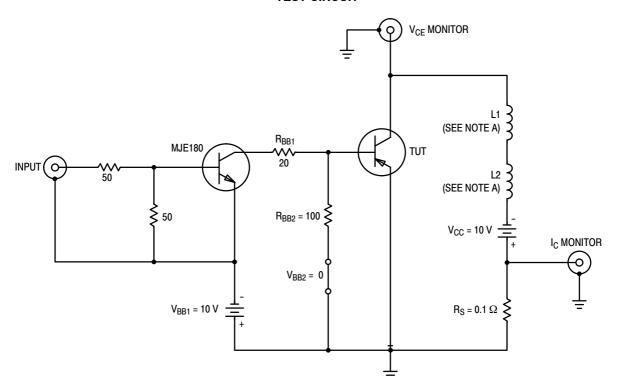
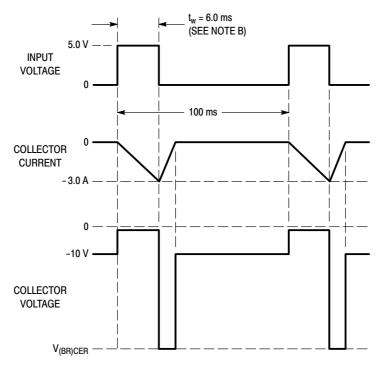


Figure 7. Maximum Rated Forward Bias Safe Operating Area

#### **TEST CIRCUIT**



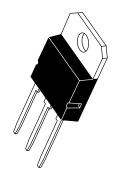
#### **VOLTAGE AND CURRENT WAVEFORMS**



#### NOTES:

- A. L1 and L2 are 10 mH, 0.11  $\Omega$ , Chicago Standard Transformer Corporation C–2688, or equivalent.
- B. Input pulse width is increased until  $I_{CM} = -3.0 \text{ A}$ .
- C. For NPN, reverse all polarities.

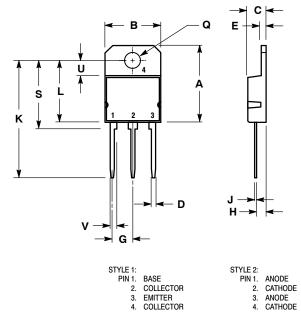
Figure 8. Inductive Load Switching



SOT-93 (TO-218) CASE 340D-02 **ISSUE E** 

**DATE 01/03/2002** 

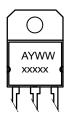




- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α		20.35		0.801
В	14.70	15.20	0.579	0.598
С	4.70	4.90	0.185	0.193
D	1.10	1.30	0.043	0.051
Е	1.17	1.37	0.046	0.054
G	5.40	5.55	0.213	0.219
Н	2.00	3.00	0.079	0.118
7	0.50	0.78	0.020	0.031
K	31.00	REF	1.220	REF
L		16.20		0.638
Q	4.00	4.10	0.158	0.161
S	17.80	18.20	0.701	0.717
U	4.00 REF		0.157	REF
V	1 75 RFF		0.0	169

#### **MARKING DIAGRAM**



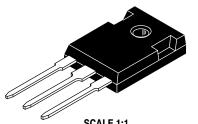
= Assembly Location

= Year

WW = Work Week XXXXX = Device Code

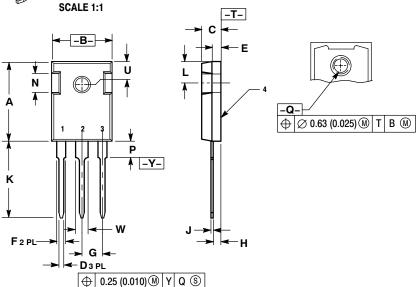
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TO-247 CASE 340L-02 ISSUE F

**DATE 26 OCT 2011** 



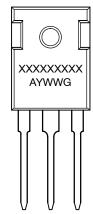
STYLE 2: PIN 1. ANODE 2. CATHODE (S) STYLE 4:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR STYLE 1: PIN 1. GATE 2. DRAIN STYLE 3: PIN 1. BASE 2. COLLECTOR 3. SOURCE 4. DRAIN 3. ANODE 2 4. CATHODES (S) 3. EMITTER 4. COLLECTOR STYLE 5: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE STYLE 6: PIN 1. MAIN TERMINAL 1 2. MAIN TERMINAL 2

3. GATE 4. MAIN TERMINAL 2

- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	20.32	21.08	0.800	8.30
В	15.75	16.26	0.620	0.640
С	4.70	5.30	0.185	0.209
D	1.00	1.40	0.040	0.055
Е	1.90	2.60	0.075	0.102
F	1.65	2.13	0.065	0.084
G	5.45 BSC		0.215 BSC	
Н	1.50	2.49	0.059	0.098
J	0.40	0.80	0.016	0.031
K	19.81	20.83	0.780	0.820
L	5.40	6.20	0.212	0.244
N	4.32	5.49	0.170	0.216
P		4.50		0.177
Q	3.55	3.65	0.140	0.144
U	6.15 BSC		0.242	BSC
W	2.87	3.12	0.113	0.123

#### **GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code = Assembly Location

Υ = Year WW = Work Week G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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D	CHANGE OF OWNERSHIP FROM MOTOROLA TO ON SEMICONDUCTOR. DIM A WAS 20.80-21.46/0.819-0.845. DIM K WAS 19.81-20.32/0.780-0.800. UPDATED STYLE 1, ADDED STYLES 2, 3, & 4. REQ. BY L. HAYES.	25 AUG 2000
E	DIM E MINIMUM WAS 2.20/0.087. DIM K MINIMUM WAS 20.06/0.790. ADDED GENERIC MARKING DIAGRAM. REQ. BY S. ALLEN.	26 FEB 2010
F	ADDED STYLES 5 AND 6. REQ. BY J. PEREZ.	26 OCT 2011

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